

## Product Data Sheet

## DIAION™ SMN1

DIAION™ SMN1 is a nuclear grade mixed resin with strongly acidic cation exchange resin, DIAION™ SKN1, and strongly basic anion exchange resin, DIAION™ SAN1. It is used for cleanup system in primary circuit, cleanup system of SFP, radwaste, etc.

## Product

Grade Name	DIAION™ SMN1
Type	Mixed
Matrix	Styrene-DVB, Gel
Functional Group	Sulfonic acid / Type I (trimethyl ammonium groups)
Ionic Form	H <sup>+</sup> / OH <sup>-</sup>
Chemical Equivalent Ratio	1 / 1

## Specification

Component		Cation Exchange Resin	Anion Exchange Resin
		DIAION™ SKN1	DIAION™ SAN1
Salt Splitting Capacity	meq/mL	1.7 min.	1.0 min.
Particle Size Distribution 425 - 1180 μm	%	95 min.	95 min.
Particle Size Distribution thr. 425 μm	%	1.0 max.	1.0 max.
Ionic Form Conversion H Form	eq%	99 min.	-
Ionic Form Conversion Na Form	eq%	0.1 max.	-
Ionic Form Conversion OH Form	eq%	-	90 min.
Ionic Form Conversion CO <sub>3</sub> Form	eq%	-	10 max.
Ionic Form Conversion Cl Form	eq%	-	0.2 max.
Metal Content (Ca)	mg/L	50 max.	50 max.
Metal Content (Pb)	mg/L	10 max.	10 max.
Metal Content (Fe)	mg/L	50 max.	-
Metal Content (Cu)	mg/L	10 max.	-
Water Extractables	g/L	0.1 max.	0.1 max.

## Typical Properties

Component		Mixed resin	
Shipping Density	g/L	720	
Component		Cation Exchange Resin	Anion Exchange Resin
		DIAION™ SKN1	DIAION™ SAN1
Mean Particle Size	μm	700	730
Particle Density	g/mL	1.20	1.07
Total Swelling (Na <sup>+</sup> to H <sup>+</sup> )	%	9	-
Total Swelling (Cl <sup>-</sup> to OH <sup>-</sup> )	%	-	23

## Recommended Operating Conditions

Maximum Operating Temperature	°C	60
Operating pH Range		0 - 14
Minimum Bed Depth	mm	800
Service Flow Rate	m/h	10 - 60



### Hydraulic Characteristics

The approximate pressure drop at various temperatures and flow rates for each meter of bed depth of DIAION™ SMN1 resin in normal down flow operation is shown in the graphs below.

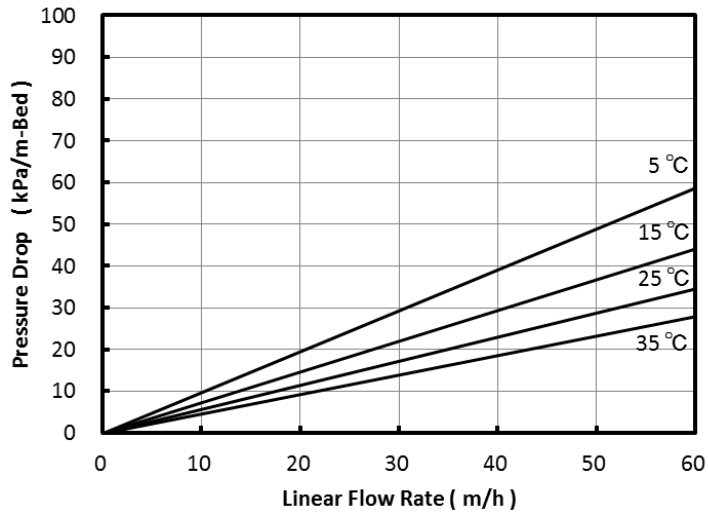


Fig. 1 Pressure Drop of SMN1

### Notice

This information are given in good faith but without warranty, and this also applies where proprietary rights of third parties are involved. The application, use and processing of our products are beyond our control and therefore your own responsibility.